

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT2599798

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>SEONG WOO LEE</td> <td>10/23/2013</td> </tr> <tr> <td>HEE BAEG AN</td> <td>10/23/2013</td> </tr> </tbody> </table>		Name	Execution Date	SEONG WOO LEE	10/23/2013	HEE BAEG AN	10/23/2013		
Name	Execution Date								
SEONG WOO LEE	10/23/2013								
HEE BAEG AN	10/23/2013								
RECEIVING PARTY DATA									
<table border="1"> <tr> <td>Name:</td> <td>MAGNACHIP SEMICONDUCTOR, LTD.</td> </tr> <tr> <td>Street Address:</td> <td>1 HYANGJEONG-DONG, HEUNGDEOK-GU, CHEONGJU-SI, CHUNGCHONGBUK-DO, 361-728</td> </tr> <tr> <td>City:</td> <td>CHEONGJU-SI</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> </table>		Name:	MAGNACHIP SEMICONDUCTOR, LTD.	Street Address:	1 HYANGJEONG-DONG, HEUNGDEOK-GU, CHEONGJU-SI, CHUNGCHONGBUK-DO, 361-728	City:	CHEONGJU-SI	State/Country:	KOREA, REPUBLIC OF
Name:	MAGNACHIP SEMICONDUCTOR, LTD.								
Street Address:	1 HYANGJEONG-DONG, HEUNGDEOK-GU, CHEONGJU-SI, CHUNGCHONGBUK-DO, 361-728								
City:	CHEONGJU-SI								
State/Country:	KOREA, REPUBLIC OF								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>14069430</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	14069430				
Property Type	Number								
Application Number:	14069430								
CORRESPONDENCE DATA									
<p>Fax Number: (202)315-3758</p> <p>Phone: 202-429-0020</p> <p>Email: pto@nsiplaw.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: NSIP LAW</p> <p>Address Line 1: P.O. BOX 65745</p> <p>Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20035</p>									
ATTORNEY DOCKET NUMBER:	023103.0091								
NAME OF SUBMITTER:	S. LAURA CHUNG								
Signature:	/S. Laura Chung/								
Date:	11/01/2013								
<p>Total Attachments: 2</p> <p>source=NewApp_0231030091_CDA_ExecutedwAppNumber#page1.tif</p> <p>source=NewApp_0231030091_CDA_ExecutedwAppNumber#page2.tif</p>									

OP \$40.00 14069430

**COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)****DECLARATION**

As a below-named inventor, I hereby declare that this declaration is directed to the application attached hereto, or to United States Application Number or PCT International Application Number

\_\_\_\_\_ filed on \_\_\_\_\_ (if applicable), entitled:

**SEMICONDUCTOR-BASED HALL SENSOR**

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the above-identified application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

I have reviewed and understand the contents of the above-identified application, including the claims.

I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37 CFR 1.56, including for continuation-in-part applications, material information that became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

**ASSIGNMENT**

For valuable consideration, I, as a below-named assignor, hereby assign to:

**MagnaChip Semiconductor, Ltd.**  
1 Hyangjeong-dong, Heungdeok-gu,  
Cheongju-si, Chungcheongbuk-do, 361-728  
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of the application identified in the above declaration, which is United States Application Number or PCT International Application Number 14/069,430 filed on November 1, 2013.


I authorize and request the attorneys appointed in the above-identified application to hereafter complete this Assignment by inserting above the application number and the filing date of the above-identified application when known, and to correct any typographical errors that may be discovered in this Assignment.

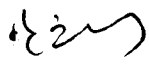
This Assignment includes the above-identified application, any and all United States and foreign patents, utility models, and design registrations granted for any of the inventions and improvements that are the subject of the above-identified application, and the right to claim priority based on the filing date of the above-identified application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and I authorize the Assignee to apply in all countries in my name or in its own name for patents, utility models, design registrations, like rights of exclusion, and inventors' certificates for any of the inventions and improvements that are the subject of the above-identified application; and I agree for myself and my heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such

**COMBINED DECLARATION AND ASSIGNMENT UNDER 37 CFR 1.63(e)**

further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In witness whereof, I, as a below-named inventor and assignor, intending to be legally bound, have hereunto affixed my signature on the date indicated below next to my signature.

Inventor's Legal Name	LEE, Seong Woo		
Inventor's Signature		Date	2013. 10. 23
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728, Republic of Korea		

Inventor's Legal Name	AN, Hee Baeg		
Inventor's Signature		Date	2013. 10. 23
Residence (City, Country)	Cheongju-si, Republic of Korea		
Mailing Address	c/o MagnaChip Semiconductor, Ltd., 1 Hyangjeong-dong, Heungdeok-gu, Cheongju-si, Chungcheongbuk-do, 361-728, Republic of Korea		